

SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING THE SAME

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ABSTRACT OF THE DISCLOSURE

10 A semiconductor device wherein in formation of
the wiring connection, an opening is made up to the
middle of the insulating film, a side wall is formed, a
burying wiring with the lower portion is arranged, a
pad is formed, and a pad is formed in a polyplug
contact without a masking step. Further, a conductive
material is filled in the hole in the insulating film,
a hole is opened in this material, a side wall is
15 formed on the inner wall, a shrunken contact is opened
by using this as a mask, and the conductive material is
filled.